



1A, 50V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- Ultrafast recovery time for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Lighting application
- Snubber
- · Freewheeling application

MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.060g (approximately)

| KEY PARAMETERS | | | |
|--------------------|----------------|------|--|
| PARAMETER | VALUE | UNIT | |
| I _F | 1 | Α | |
| V_{RRM} | 50 - 1000 | V | |
| I _{FSM} | 30 | Α | |
| T _{J MAX} | 150 | °C | |
| Package | DO-214AC (SMA) | | |
| Configuration | Single die | | |









DO-214AC (SMA)



| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | | l | | | |
|--|------------------|--------------|------|------|------|------|------|------|------|
| PARAMETER | SYMBOL | US1A | US1B | US1D | US1G | US1J | US1K | US1M | UNIT |
| Marking code on the device | | US1A | US1B | US1D | US1G | US1J | US1K | US1M | |
| Repetitive peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Reverse voltage, total rms value | $V_{R(RMS)}$ | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Forward current | I _F | 1 | | | | Α | | | |
| Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load | I _{FSM} | 30 | | | | А | | | |
| Junction temperature | TJ | - 55 to +150 | | | °C | | | | |
| Storage temperature | T _{STG} | - 55 to +150 | | | °C | | | | |

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| THERMAL PERFORMANCE | | | | |
|--|-----------------|-----|------|--|
| PARAMETER | SYMBOL | TYP | UNIT | |
| Junction-to-lead thermal resistance | $R_{\Theta JL}$ | 27 | °C/W | |
| Junction-to-ambient thermal resistance | $R_{\Theta JA}$ | 75 | °C/W | |

| PARAMETER | | CONDITIONS | SYMBOL | TYP | MAX | UNIT |
|---|------------------------------|--|------------------|-----|-----|------|
| Forward voltage ⁽¹⁾ | US1A US1B US1D US1G | I _F = 1A, T _J = 25°C | V _F | - | 1.0 | V |
| | US1J US1K US1M | | | - | 1.7 | V |
| Reverse current @ rated V _R ⁽²⁾ | | T _J = 25°C | | - | 5 | μΑ |
| | | T _J = 125°C | - I _R | - | 150 | μΑ |
| Junction capacitance | US1A US1B US1D US1G | 1MHz, V _R = 4.0V | CJ | 15 | - | pF |
| · | US1J US1K US1M | | | 10 | - | pF |
| Reverse recovery time | US1A US1B US1D US1G | I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A | t _{rr} | - | 50 | ns |
| · | US1J US1K US1M | | | - | 75 | ns |

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

| ORDERING INFORMATION | | |
|------------------------------|----------------|---------------------|
| ORDERING CODE ⁽¹⁾ | PACKAGE | PACKING |
| US1x | DO-214AC (SMA) | 7,500 / Tape & Reel |

Notes:

1. "x" defines voltage from 50V(US1A) to 1000V(US1M)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

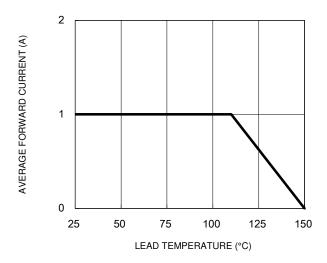


Fig.3 Typical Reverse Characteristics

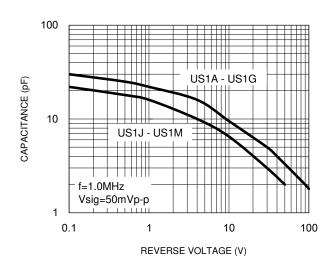
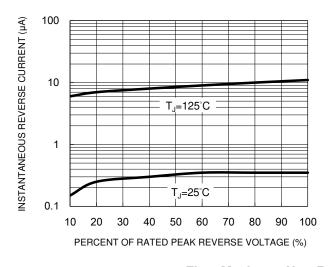


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



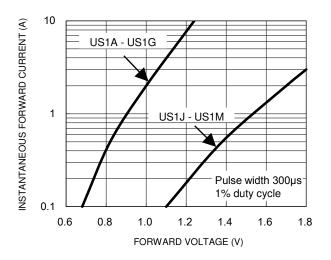
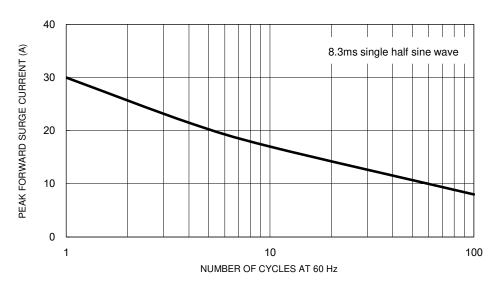


Fig.5 Maximum Non-Repetitive Forward Surge Current





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Typical Transient Thermal Characteristics

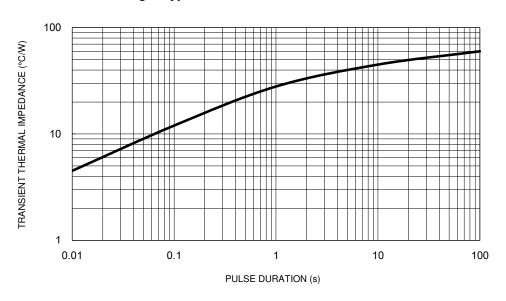
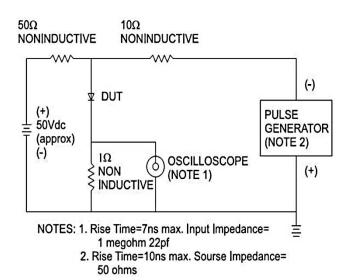
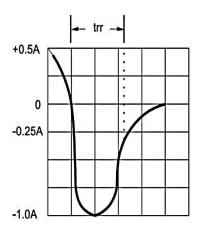


Fig.7 Reverse Recovery Time Characteristic And Test Circuit Diagram



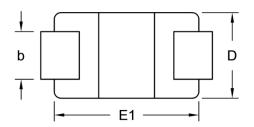


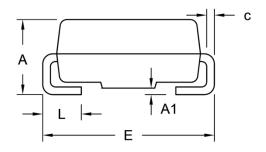




PACKAGE OUTLINE DIMENSIONS

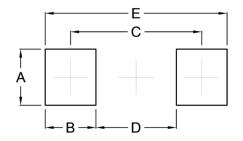
DO-214AC (SMA)





| DIM. | Unit (mm) | | Unit (| (inch) |
|--------|-----------|------|--------|--------|
| Dilvi. | Min. | Max. | Min. | Max. |
| Α | 1.99 | 2.50 | 0.078 | 0.098 |
| A1 | 0.10 | 0.20 | 0.004 | 0.008 |
| b | 1.27 | 1.58 | 0.050 | 0.062 |
| С | 0.15 | 0.31 | 0.006 | 0.012 |
| D | 2.29 | 2.83 | 0.090 | 0.111 |
| E | 4.95 | 5.33 | 0.195 | 0.210 |
| E1 | 4.06 | 4.60 | 0.160 | 0.181 |
| L | 0.90 | 1.41 | 0.035 | 0.056 |

SUGGESTED PAD LAYOUT



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| Α | 1.68 | 0.066 |
| В | 1.52 | 0.060 |
| С | 3.93 | 0.155 |
| D | 2.41 | 0.095 |
| E | 5.45 | 0.215 |

MARKING DIAGRAM



= Marking Code P/N G = Green Compound

ΥW = Date Code F = Factory Code



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